

Features

1. Ideal for printed circuit board
2. Reliable low cost construction utilizing molded plastic
3. technique High temperature soldering guaranteed: 260°/10 seconds at 5 lbs., (2.3kg) tension
4. Small size, simple installation
5. High surge current capability
6. Glass passivated chip junction

Mechanical Data

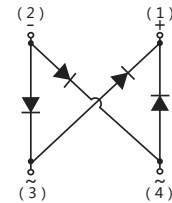
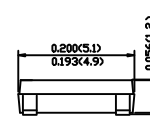
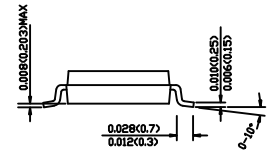
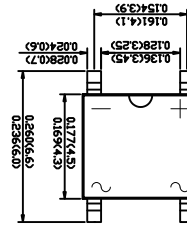
Case : JEDEC ABF Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750,Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : 82mg 0.0029oz

ABF



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	AB2F	AB4F	AB6F	AB8F	AB10F	UNITS
		AB2F	AB4F	AB6F	AB8F	AB10F	
Marking Code		AB2F	AB4F	AB6F	AB8F	AB10F	
Maximum repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	200	400	600	800	1000	V
Maximum average forward rectified current	$I_{F(AV)}$	1.0					A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30					A
Maximum instantaneous forward voltage drop per leg at 1A	V_F	1.1					V
Maximum DC reverse current at rated DC blocking voltage $T_A=25^\circ\text{C}$ $T_A=100^\circ\text{C}$	I_R	5 50					μA
Typical thermal resistance	$R_{\theta JA}$	75					$^\circ\text{C}/\text{W}$
Typical junction capacitance	C_j	13					pF
Operating temperature range	T_J	-55 to +150					$^\circ\text{C}$
storage temperature range	T_{STG}	-55 to +150					$^\circ\text{C}$

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.

Ratings And Characteristic Curves

FIG.1 TYPICAL FORWARD CHARACTERISTICS

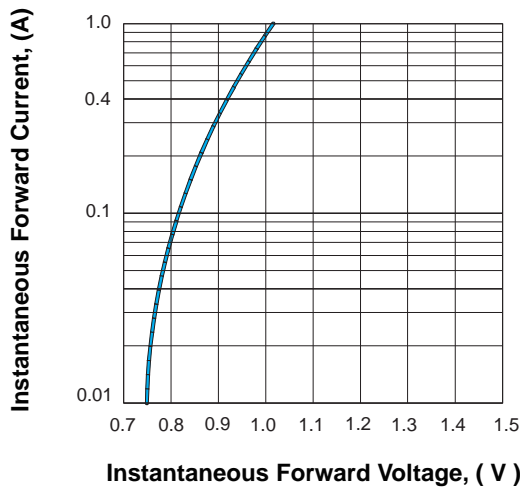


FIG.2 FORWARD DERATING CURVE

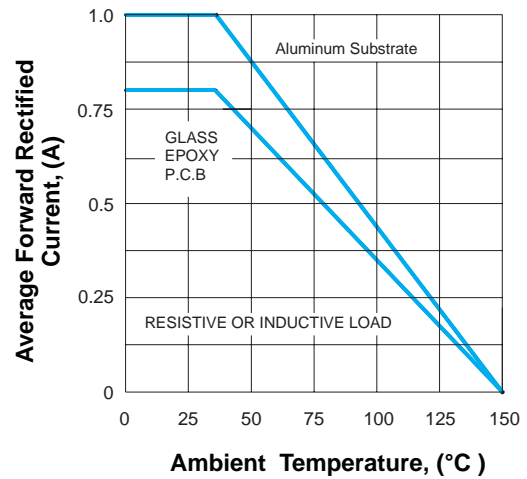


FIG.3 TYPICAL REVERSE CHARACTERISTICS

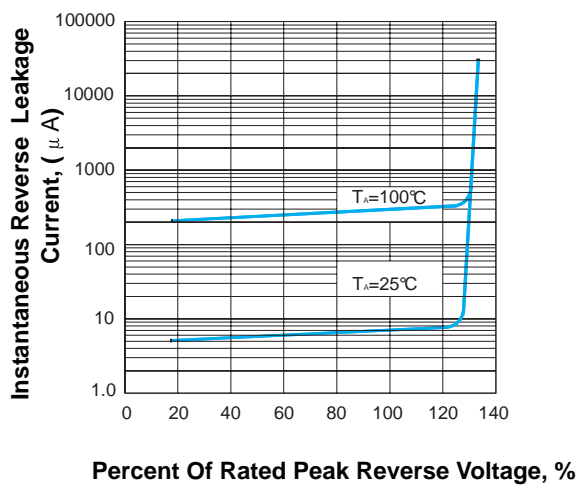
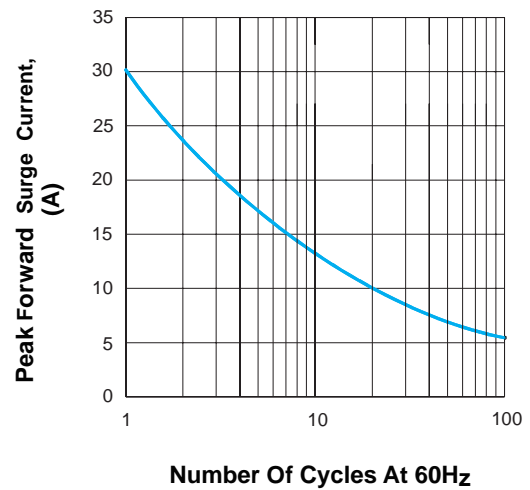
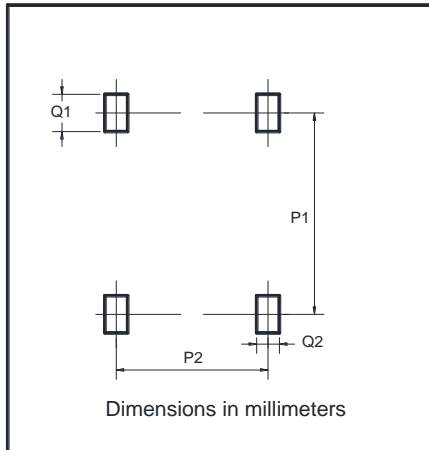


FIG.4 PEAK FORWARD SURGE CURRENT



Suggested Pad Layout



Dim	Min
P1	5.72
P2	4.00
Q1	1.00
Q2	0.90